

10:30 Coffee Break

Session SS Special Session Space and Aeronautic systems

Room Cassiopée

chairpersons M. LABRUNEE
P. PONS

10:50 **SS-1
#17** *Stress factors in aircraft electronics: superimpositions, case studies and failure precautions*
P. Jacob, G. Nicoletti
Empa Swiss Fed Labs for Materials Testing and Research

11:10 **SS-2
#25** *A closed-loop voltage prognosis for lithium-ion batteries under dynamic loads using an improved equivalent circuit model*
J. Yang¹, J. Yu¹, D. Tang¹, J. Dai²
¹Beihang University, ²China Academy of Launch Vehicle Technology R&D Center

11:30 **SS-3
#84** *Combined Ionizing Radiation & Electromagnetic Interference Test Procedure to Achieve Reliable Integrated Circuits*
F. Vargas¹, R. Goerl¹, P. Villa², N. Medina³, N. Added³, M. Da Silva⁴
¹Catholic University - PUCRS, ²Federal Institute of Rio Grande do Sul - IFRS, ³University of São Paulo, ⁴Centro Universitário FEI

11:50 **SS-4
#127** *Robustness and Reliability Review of Si and SiC FET devices for More-Electric-Aircraft Applications*
J. Ortiz Gonzalez, R. Wu, S. N. Agbo, O. Alatisse
The University of Warwick

12:10 **SS-5
#219** *Reliability evaluation of a 0.25µm SiGe technology for space applications*
C. Robin, S. Rochette
Thales Alenia Space

12:30 **SS-6
#241** *Radiation-induced Single Event Transient effects during the Reconfiguration Process of SRAM-based FPGAs*
L. Sterpone, C. De Sio, L. Bozzoli, S. Azimi, B. Du
Politecnico di Torino

12:50 Lunch

Session I1-I2 ESD and EMC

Room Cassiopée

chairpersons D. POGANY
T. DUBOIS

14:00 Invited paper
EMC & ESD from the technology to the system (Challenge, Trends, application cases)
P. Besse
NXP Semiconductors

14:40 **I1-
I2-1
#37** *Effect of TLP rise time on ESD failure modes of collector-base junction of SiGe heterojunction bipolar transistors*
C. Fleury¹, D. Pogany², W. Simbürger³
¹CTR Carinthian Tech Research AG, ²Vienna University of Technology, ³Infineon

15:00 **I1-
I2-2
#39** *Topology and design investigation on thin film silicon BIMOS device for ESD protection in FD-SOI technology*
P. Galy¹, L. De Conti², M. Vinet³, S. Cristoloveanu⁴,